



10/008443 #5
S01P1821US00J
6640/66050

DECLARATION AND POWER OF ATTORNEY

As a below-named inventor, I hereby declare that:

My residence, post office address, and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

INFORMATION PROCESSING APPARATUS AND INFORMATION PROCESSING METHOD, NETWORK SYSTEM, RECORDING MEDIUM, AND COMPUTER PROGRAM

the specification of which
(check one)

_____ is attached hereto.

X was filed on December 3, 2001 as _____

Application Serial No. 10/008,443

and was amended on _____
(if applicable)

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information of which I am aware which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)			Priority Claimed	
<u>Number</u>	<u>Country</u>	<u>Filing Date</u>	<u>Yes</u>	<u>No</u>
<u>P2000-371561</u>	<u>Japan</u>	<u>December 6, 2000</u>	<u>X</u>	—

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Declaration and Power of Attorney

Page 2

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States Application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

<u>Application Serial No.</u>	<u>Filing Date</u>	<u>Status</u>
_____	_____	_____
_____	_____	_____

And I hereby appoint Jay H. Maioli, Reg. No. 27,213; Donald S. Dowden, Reg. No. 20,701; William E. Pelton, Reg. No. 25,702; Peter J. Phillips, Reg. No. 29,691; Gerald W. Griffin, Reg. No. 18,886; Ivan S. Kavrukov, Reg. No. 25,161; Christopher C. Dunham, Reg. No. 22,031; Norman H. Zivin, Reg. No. 25,385; John P. White, Reg. No. 28,678; and Robert D. Katz, Reg. No. 30,141; and each and all of them, all c/o Cooper & Dunham, 1185 Avenue of the Americas, New York, NY 10036 (Tel. (212) 278-0400), my attorneys, each with full power of substitution and revocation, to receive the patent, to transact all business in the Patent and Trademark Office connected therewith and to file any International Applications which are based thereon under the provisions of the Patent Cooperation Treaty.

Please address all communications, and direct all telephone calls, regarding this application to

JAY H. MAIOLI
Cooper & Dunham LLP
1185 Avenue of the Americas
New York, New York 10036
Tel. (212) 278-0400

Reg. No. 27,213

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or

First joint inventor Yasumasa Mizushima

Inventor's signature _____

Citizenship Japanese

Date of Signature

January 9, 2002

Residence Kanagawa, Japan

Post Office Address c/o Sony Logistics Corporation, 7-35 Kitashinagawa, 6-chome

Shinagawa-ku, Tokyo, JAPAN

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Full name of

Second joint inventor Masami Kinugasa

Inventor's signature

Masami Kinugasa

Citizenship Japanese

Date of Signature

Jan 10/2002

Residence Tokyo, Japan

Post Office Address c/o Sony Logistics Corporation, 7-35 Kitashinagawa, 6-chome

Shinagawa-ku, Tokyo, JAPAN

Full name of

Third joint inventor Zenta Watanabe

Inventor's signature

Zenta Watanabe

Citizenship Japanese

Date of Signature

Jan 10, 2002

Residence Tokyo, Japan

Post Office Address c/o Sony Logistics Corporation, 7-35 Kitashinagawa, 6-chome

Shinagawa-ku, Tokyo 141, JAPAN

Full name of

Fourth joint inventor Masakatsu Mori

Inventor's signature

Masaki Mori

Citizenship Japanese

Date of Signature

Jan 15, 2002

Residence Kanagawa, Japan

Post Office Address c/o Accenture Corporation, Nihon Seimei Akasaka Daini Building, 7-1-16, Akasaka,

Minato-ku, Tokyo, Japan

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Full name of

Fifth joint inventor Fumio Koyama

Inventor's signature

Citizenship Japanese

Date of Signature Jan. 30, 2002

Residence Chiba, Japan

Post Office Address c/o Accenture Corporation, Nihon Seimei Akasaka Daini Building, 7-1-16, Akasaka,
Minato-ku, Tokyo, Japan

Full name of

Sixth joint inventor Nobuaki Katsuya

Inventor's signature

Citizenship Japanese

Date of Signature Jan 30, 2002

Residence Saitama, Japan

Post Office Address c/o Accenture Corporation, Nihon Seimei Akasaka Daini Building, 7-1-16, Akasaka,
Minato-ku, Tokyo, Japan

Full name of

Seventh joint inventor Koji Hagioda

Inventor's signature

Citizenship Japanese

Date of Signature

Residence Kanagawa, Japan

Post Office Address c/o Accenture Corporation, Nihon Seimei Akasaka Daini Building, 7-1-16, Akasaka,
Minato-ku, Tokyo, Japan

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Full name of
Eighth joint inventor Haruyo Endo
Inventor's signature *Haruyo Endo*
Citizenship Japanese Date of Signature Feb 8, 2002
Residence Tokyo, Japan
Post Office Address c/o Accenture Corporation, Nihon Seimei Akasaka Daini Building, 7-1-16, Akasaka,
Minato-ku, Tokyo, Japan

Full name of
Ninth joint inventor Yukihiro Fukuta
Inventor's signature *Yukihiro Fukuta*
Citizenship Japanese Date of Signature Feb 8, 2002
Residence Tokyo, Japan
Post Office Address c/o Accenture Corporation, Nihon Seimei Akasaka Daini Building, 7-1-16, Akasaka,
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RECORDATION FORM COVER SHEET

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PATENTS ONLY

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Yasumasa Mizushima, Masami Kinugasa, Zenta Watanabe,
Masakatsu Mori, Fumio Koyama, Nobuaki Katsuya, Haruyo Endo,
Yukihiro Fukuta, Koji Hagioda

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

Name and address of receiving party(ies):

Name: Sony Corporation

Internal Address: _____

3. Nature of Conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other _____

Execution Dates: Jan. 9, 2002, Jan. 10, 2002, Jan. 15, 2002, Jan. 30, 2002,
Feb. 8, 2002

Street Address: 7-35 Kitashinagawa 6-chome

Shinagawa-ku, Tokyo, Japan

City _____ State _____ ZIP _____

Additional name(s) & address(es) attached? ☒ Yes ☐ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is _____

A. Patent Application No.(s)

10/008,443

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Jay H. Maioli

Internal Address: Cooper & Dunham LLP

Street Address: 1185 Avenue of the Americas

City: New York State: New York ZIP: 10036

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 40.00

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit account number:

03-3125

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Jay H. Maioli, Reg. No. 27,213

Name of Person Signing

Signature

Date

05.01.02

Total Number of pages comprising cover sheet: 2

OMB No. 0651-0011 (exp. 4/94)

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Additional Names and Addresses of Receiving Parties:

Accenture Corporation
Nihon Seimei Akasaka Daini Building
7-1-16, Akasaka Minato-ku
Tokyo, Japan

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in INFORMATION PROCESSING APPARATUS AND INFORMATION PROCESSING METHOD, NETWORK SYSTEM, RECORDING MEDIUM, AND COMPUTER PROGRAM for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 6-7-35 Kitashinagawa, Shinagawa-Ku, Tokyo, Japan and Accenture Corporation, Nihon Seimei Akasaka Daini Building, 7-1-16, Akasaka Minato-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEES) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereof;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereof;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the

This assignment executed on the dates indicated below.

Yasumasa Mizushima

Name of first or sole inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor

Signature of first or sole inventor

Yasumasa Mizushima, January 9, 2002
Date of this assignment

Masami Kinugasa

Name of second inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Signature of second inventor

Masami Kinugasa, Jan 10/2002
Date of this assignment

Zenta Watanabe

Name of third inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of third inventor

Signature of third inventor

Zenta Watanabe, Jan 10, 2002
Date of this assignment

Masakatsu Mori

Name of fourth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fourth inventor

Signature of fourth inventor

Masakatsu Mori, Jan 15, 2002
Date of this assignment

Fumio Koyama

Name of fifth inventor

Execution date of U.S. Patent Application

Chiba, Japan

Residence of fifth inventor

Signature of fifth inventor

Fumio Koyama, JAN. 15, 2002
Date of this assignment

Nobuaki Katsuya

Name of sixth inventor

Execution date of U.S. Patent Application

Saitama, Japan

Residence of sixth inventor

Nobuaki Katsuya

Signature of sixth inventor

Jan 30, 2002

Date of this assignment

Koji Hagioda

Name of seventh inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of seventh inventor

Signature of seventh inventor

Date of this assignment

Haruyo Endo

Name of eighth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of eighth inventor

Haruyo Endo

Signature of eighth inventor

Feb 8, 2002

Date of this assignment

Yukihiro Fukuta

Name of ninth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of ninth inventor

Yukihiro Fukuta

Signature of ninth inventor

Feb 8, 2002

Date of this assignment